

Patent Abstracts of Japan

PUBLICATION NUMBER : 07030152  
PUBLICATION DATE : 31-01-95

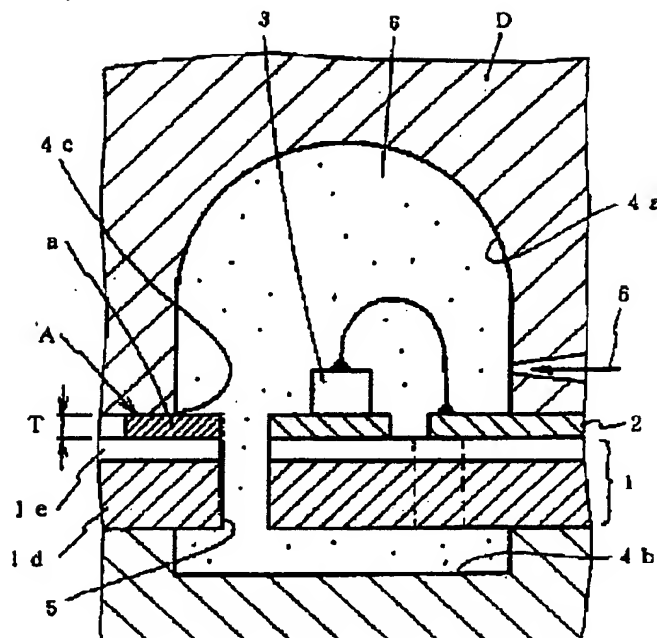
APPLICATION DATE : 09-07-93  
APPLICATION NUMBER : 05170603

APPLICANT : MITSUBISHI CABLE IND LTD;

INVENTOR : SANO SHINICHI;

INT.CL. : H01L 33/00 H01L 21/56 H01L 23/28  
H05K 3/28

TITLE : MOLDING METHOD FOR ELECTRONIC  
COMPONENT MOUNTED ON BOARD  
AND BOARD STRUCTURE FOR  
MOLDING



ABSTRACT : PURPOSE: To provide a molding method wherein a high-quality resin coating layer without any burr can be formed and an insulating layer on the surface of a board is not stripped and to provide a board structure, for molding, which is suitable for the molding method when an electronic component, especially an LED chip, which has been mounted on a printed-circuit board, a display panel or the like is molded.

CONSTITUTION: When a resin molding operation is executed, by using a metal mold, to an electronic component 3 mounted on a circuit pattern 2 on a board 1, a spacer pattern (a) in addition to the circuit pattern 2 is formed in advance around a part corresponding to the boundary line 4c of the resin molding operation at least on the board 1. Then, in the molding method of the electronic component mounted on the board, the outer circumferential edge 4c of a metal- mold cavity 4a is moved along the spacer pattern (a), a mold D is set in a prescribed position, and a molding resin 6 is injected into the cavity 4a. In addition, a board structure A for molding is suitable for the molding method.

COPYRIGHT: (C)1995,JPO